

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.71762	100.0	53.06
Subtotal				0.71762	100	53.06
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00165	100.0	0.12231
	Pure metal	Aluminium (Al)	7429-90-5	0.13304	100.0	9.83664
Subtotal				0.13469	200	9.95895
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0197	0.03	1.4568
	Copper alloy	Iron (Fe)	7439-89-6	0.06568	0.1	4.856
	Copper alloy	Copper (Cu)	7440-50-8	65.59084	99.87	4,849.6872
Subtotal				65.67622	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.31461	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.92977	15.0	364.5
	Filler	Silica fused	60676-86-0	24.32022	74.0	1,798.2
	Flame retardant	Metal hydroxide		2.30056	7.0	170.1
Subtotal				32.86516	100	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.40574	100.0	30
Subtotal				0.40574	100	30
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.13037	65.0	9.63934
	Lead alloy	Silver (Ag)	7440-22-4	0.05014	25.0	3.70744
	Lead alloy	Antimony (Sb)	7440-36-0	0.02006	10.0	1.48298
Subtotal				0.20057	100	14.82976
Total				100	100	NaN

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